

Wafer Cutting Machine - WC 5



❖ High Capacity

❖ Quality Cuts

❖ Easy Cleaning

Better by design...

Wafer Cutting Machine (WC-Series)

These machine take over the cooled-down wafer blocks coming from the cooling device or creaming machine and cut them into required number of blocks. These are used for cutting flat and hollow wafers filled with cream. In the cutting operation the first cut is made through the width of the stack, and the second cut is a longitudinal one. Fixed and tensioned cutting wires in removable frames are used to cut the wafers. Change over to other cutting sizes is facilitate by quickly and easily changing the cutting frames and pushers.

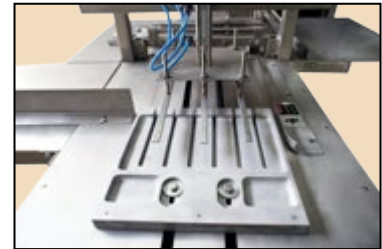
Operation Of The WC Machine

A number of wafer blocks having together a height of about 70mm can be put between pressing piece and cutting frame of the first table and lightly pressed to the pressing piece as well as to the striking point. It is necessary that the block lie at the striking point if both sides of the block are to be cut evenly. If after the first cut, it shows that the two waste strips are not equally wide; this can be corrected by adjusting the striking point. During practical operations it has shown that the width of the waste strip should be about 5mm, which is absolutely necessary if the entire block is to be cut cleanly.

Now it must be decided whether one wishes to work with non-automatic or automatic operation. The difference between these two possibilities consists in the fact that, in case of non-automatic operation, the button must be pushed for each individual switches on the first sliding carriage to new movement as soon as it returns to the cutting procedure. Whilst in case of automatic operation the second sliding carriage initial position.

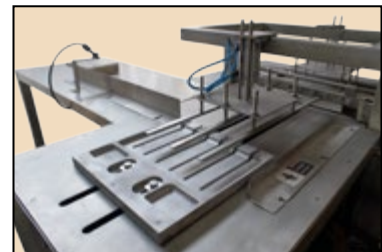
WC5 Machine Features

This machine is attached with a pneumatic pusher. The wafer books coming from the Book Cooler are fed to the cutting machine through intermediate conveyor where in first the pneumatic pusher allows the wafer book to feed them at first cu and simultaneously a gentle press is applied for a gentle press required for the stack wafer books at the process of cutting.



Technical Details

Type	WC 5 - 1	WC 5 - 2
Size of the plate (in mm approx)	290 x 460	350 x 470
Stack height (in mm)	70	70
Minimum cutting width (in mm)	18	18
Cutting Wire (spring steel) (in mm)	0.5	0.5
Connected load (in Kw)	1.5	1.5
Dimensions (in mm)		
Length	2400	2400
Width	1700	1700
Height	1200	1200
Net Weight (apprx)	480	480
Shipping volume (CBM)	4.5	4.5



*Modifications Reserved

We are constantly guided by our principle of offering our customers better and better machines; to give increased efficiency and higher levels of automation. The technical data and illustrations are subject to change without notice

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